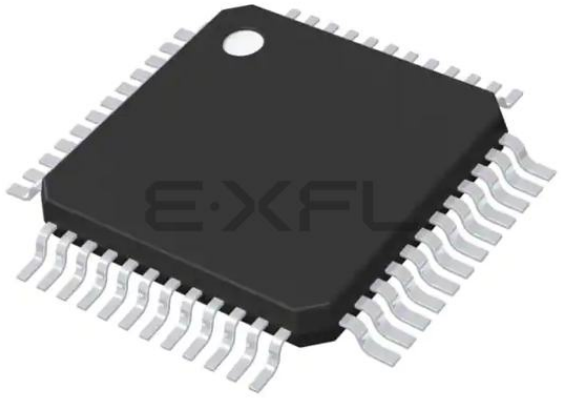
Infineon Technologies - XC8866FFA5VACKXUMA1 Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	PG-TQFP-48
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc8866ffa5vackxuma1

2 General Device Information

Chapter 2 contains the block diagram, pin configurations, definitions and functions of the XC886/888.

2.1 Block Diagram

The block diagram of the XC886/888 is shown in **Figure 2**.

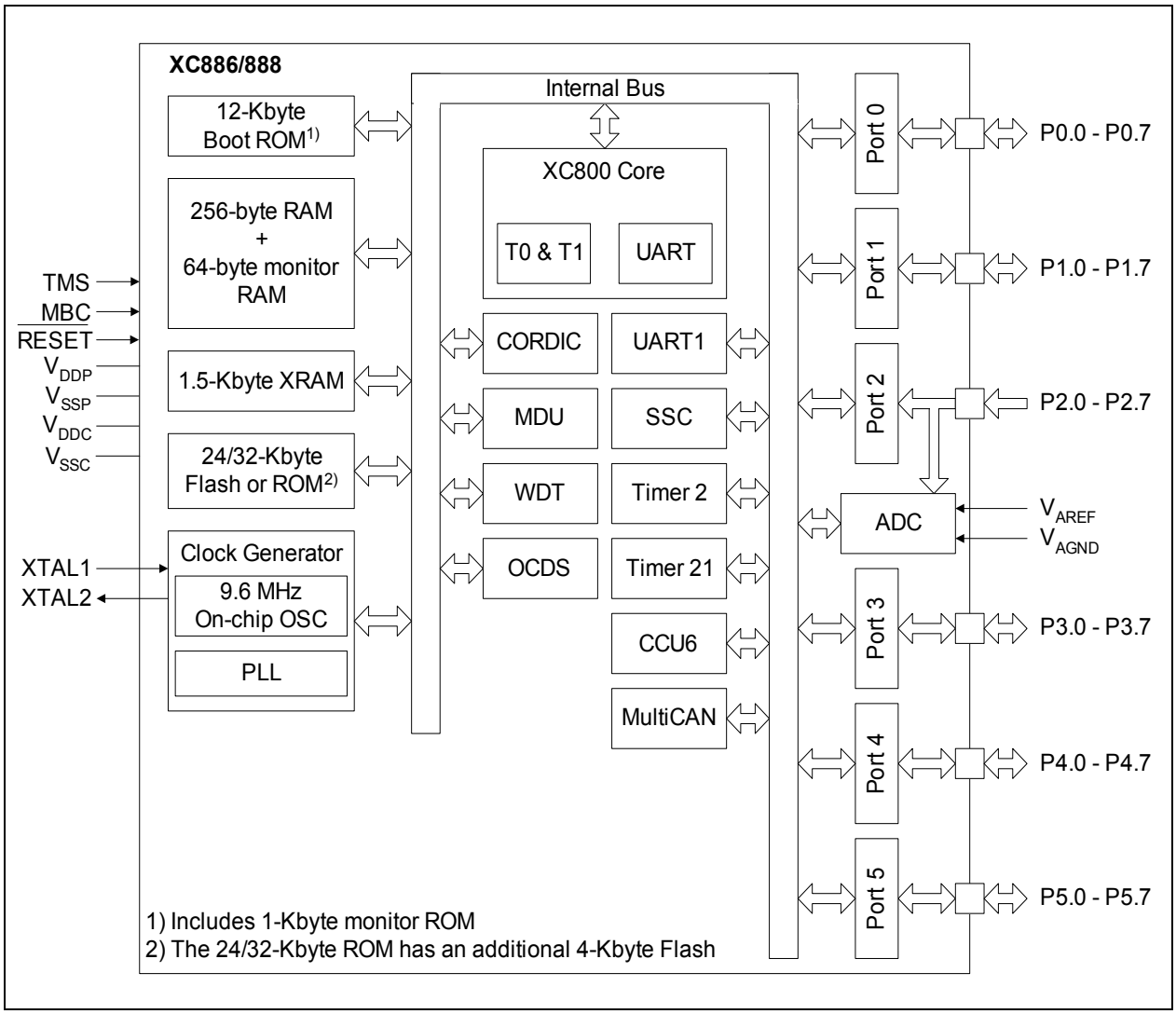


Figure 2 XC886/888 Block Diagram

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function	
P1		I/O		**Port 1** Port 1 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, Timer 0, Timer 1, Timer 2, Timer 21, MultiCAN and SSC.	
P1.0	26/34		PU	RXD_0 T2EX RXDC0_0	UART Receive Data Input Timer 2 External Trigger Input MultiCAN Node 0 Receiver Input
P1.1	27/35		PU	EXINT3 T0_1 TDO_1 TXD_0 TXDC0_0	External Interrupt Input 3 Timer 0 Input JTAG Serial Data Output UART Transmit Data Output/Clock Output MultiCAN Node 0 Transmitter Output
P1.2	28/36		PU	SCK_0	SSC Clock Input/Output
P1.3	29/37		PU	MTSR_0 TXDC1_3	SSC Master Transmit Output/Slave Receive Input MultiCAN Node 1 Transmitter Output
P1.4	30/38		PU	MRST_0 EXINT0_1 RXDC1_3	SSC Master Receive Input/ Slave Transmit Output External Interrupt Input 0 MultiCAN Node 1 Receiver Input
P1.5	31/39		PU	CCPOS0_1 EXINT5 T1_1 EXF2_0 RXDO_0	CCU6 Hall Input 0 External Interrupt Input 5 Timer 1 Input Timer 2 External Flag Output UART Transmit Data Output

Table 9 WDT Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
BE_H	**WDTL** **Reset: 00_H** Watchdog Timer Register Low	Bit Field	WDT							
		Type	rh							
BF_H	**WDTH** **Reset: 00_H** Watchdog Timer Register High	Bit Field	WDT							
		Type	rh							

3.2.4.6 Port Registers

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$B2_H$	**PORT_PAGE** **Reset: 00_H** Page Register	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, PAGE 0										
80_H	**P0_DATA** **Reset: 00_H** P0 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_DIR** **Reset: 00_H** P0 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_DATA** **Reset: 00_H** P1 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_DIR** **Reset: 00_H** P1 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_DATA** **Reset: 00_H** P5 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
93_H	**P5_DIR** **Reset: 00_H** P5 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A0_H$	**P2_DATA** **Reset: 00_H** P2 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_DIR** **Reset: 00_H** P2 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_DATA** **Reset: 00_H** P3 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_DIR** **Reset: 00_H** P3 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C8_H$	**P4_DATA** **Reset: 00_H** P4 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C9_H$	**P4_DIR** **Reset: 00_H** P4 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Table 10 Port Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0, PAGE 1										
80_H	**P0_PUDSEL Reset: FF_H** P0 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_PUDEN Reset: $C4_H$** P0 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_PUDSEL Reset: FF_H** P1 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_PUDEN Reset: FF_H** P1 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_PUDSEL Reset: FF_H** P5 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
93_H	**P5_PUDEN Reset: FF_H** P5 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A0_H$	**P2_PUDSEL Reset: FF_H** P2 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_PUDEN Reset: 00_H** P2 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_PUDSEL Reset: BF_H** P3 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_PUDEN Reset: 40_H** P3 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C8_H$	**P4_PUDSEL Reset: FF_H** P4 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$C9_H$	**P4_PUDEN Reset: 04_H** P4 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, PAGE 2										
80_H	**P0_ALTSEL0 Reset: 00_H** P0 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86_H	**P0_ALTSEL1 Reset: 00_H** P0 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90_H	**P1_ALTSEL0 Reset: 00_H** P1 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91_H	**P1_ALTSEL1 Reset: 00_H** P1 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92_H	**P5_ALTSEL0 Reset: 00_H** P5 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FE_H	**CCU6_CMPSTATL Reset: 00_H** Compare State Register Low	Bit Field	0	CC63 ST	CC POS2	CC POS1	CC POS0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF_H	**CCU6_CMPSTATH Reset: 00_H** Compare State Register High	Bit Field	T13IM	COUT 63PS	COUT 62PS	CC62 PS	COUT 61PS	CC61 PS	COUT 60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

3.2.4.11 UART1 Registers

The UART1 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 15 UART1 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$C8_H$	**SCON Reset: 00_H** Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
$C9_H$	**SBUF Reset: 00_H** Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
CA_H	**BCON Reset: 00_H** Baud Rate Control Register	Bit Field	0				BRPRE			R
		Type	r				rw			rw
CB_H	**BG Reset: 00_H** Baud Rate Timer/Reload Register	Bit Field	BR_VALUE							
		Type	rwh							
CC_H	**FDCON Reset: 00_H** Fractional Divider Control Register	Bit Field	0					NDOV	FDM	FDEN
		Type	r					rwh	rw	rw
CD_H	**FDSTEP Reset: 00_H** Fractional Divider Reload Register	Bit Field	STEP							
		Type	rw							
CE_H	**FDRES Reset: 00_H** Fractional Divider Result Register	Bit Field	RESULT							
		Type	rh							

3.7 Reset Control

The XC886/888 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC886/888 is first powered up, the status of certain pins (see **Table 23**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9*V_{DDC}. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* $V_{DDC.}$

A typical application example is shown in **Figure 22**. The V_{DDP} capacitor value is 100 nF while the V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the $\overline{\text{RESET}}$ pin should be held low for 500 µs typically. See **Figure 23**.

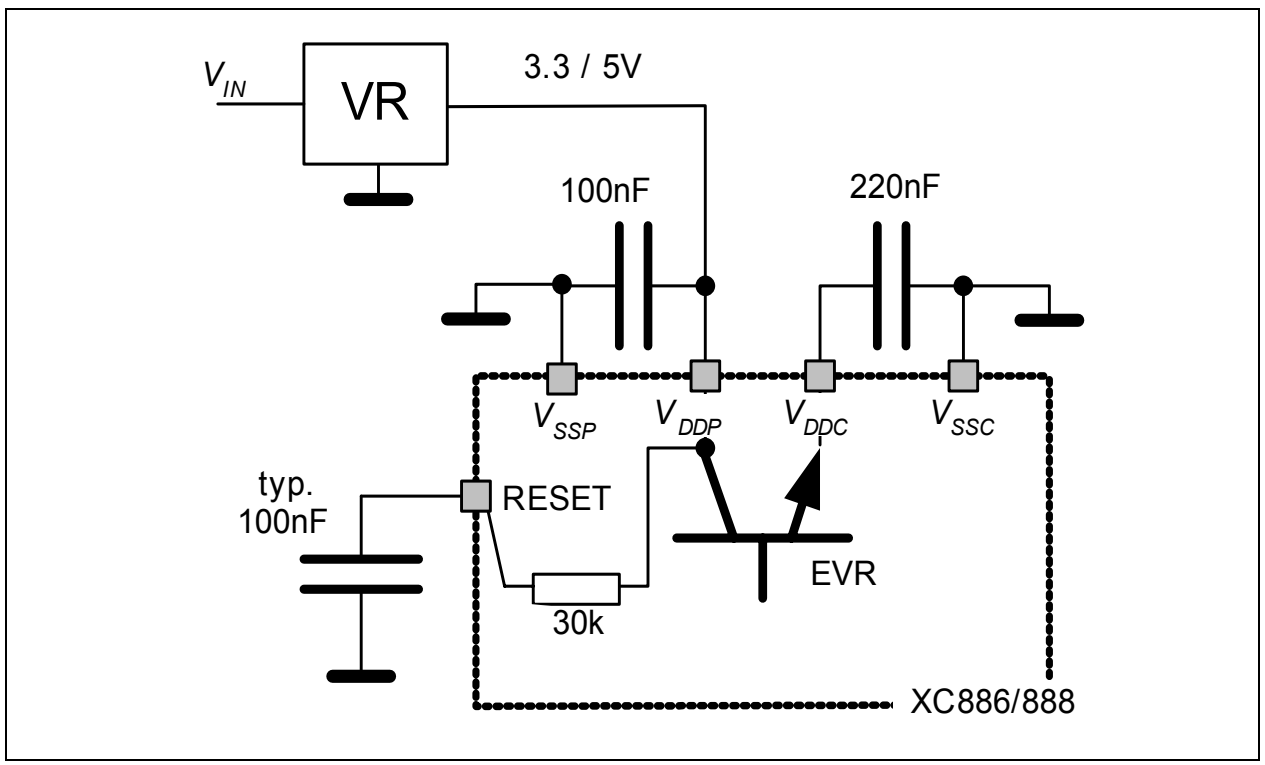


Figure 22 Reset Circuitry

3.11 Multiplication/Division Unit

The Multiplication/Division Unit (MDU) provides fast 16-bit multiplication, 16-bit and 32-bit division as well as shift and normalize features. It has been integrated to support the XC886/888 Core in real-time control applications, which require fast mathematical computations.

Features

- Fast signed/unsigned 16-bit multiplication
- Fast signed/unsigned 32-bit divide by 16-bit and 16-bit divide by 16-bit operations
- 32-bit unsigned normalize operation
- 32-bit arithmetic/logical shift operations

Table 28 specifies the number of clock cycles used for calculation in various operations.

Table 28 MDU Operation Characteristics

Operation	Result	Remainder	No. of Clock Cycles used for calculation
Signed 32-bit/16-bit	32-bit	16-bit	33
Signed 16-bit/16bit	16-bit	16-bit	17
Signed 16-bit x 16-bit	32-bit	-	16
Unsigned 32-bit/16-bit	32-bit	16-bit	32
Unsigned 16-bit/16-bit	16-bit	16-bit	16
Unsigned 16-bit x 16-bit	32-bit	-	16
32-bit normalize	-	-	No. of shifts + 1 (Max. 32)
32-bit shift L/R	-	-	No. of shifts + 1 (Max. 32)

3.12 CORDIC Coprocessor

The CORDIC Coprocessor provides CPU with hardware support for the solving of circular (trigonometric), linear (multiply-add, divide-add) and hyperbolic functions.

Features

- Modes of operation
  - Supports all CORDIC operating modes for solving circular (trigonometric), linear (multiply-add, divide-add) and hyperbolic functions
  - Integrated look-up tables (LUTs) for all operating modes
- Circular vectoring mode: Extended support for values of initial X and Y data up to full range of $[-2^{15},(2^{15}-1)]$ for solving angle and magnitude
- Circular rotation mode: Extended support for values of initial Z data up to full range of $[-2^{15},(2^{15}-1)]$, representing angles in the range $[-\pi,((2^{15}-1)/2^{15})\pi]$ for solving trigonometry
- Implementation-dependent operational frequency of up to 80 MHz
- Gated clock input to support disabling of module
- 16-bit accessible data width
  - 24-bit kernel data width plus 2 overflow bits for X and Y each
  - 20-bit kernel data width plus 1 overflow bit for Z
  - With KEEP bit to retain the last value in the kernel register for a new calculation
- 16 iterations per calculation: Approximately 41 clock-cycles or less, from set of start (ST) bit to set of end-of-calculation flag, excluding time taken for write and read access of data bytes.
- Twos complement data processing
  - Only exception: X result data with user selectable option for unsigned result
- X and Y data generally accepted as integer or rational number; X and Y must be of the same data form
- Entries of LUTs are 20-bit signed integers
  - Entries of atan and atanh LUTs are integer representations (S19) of angles with the scaling such that $[-2^{15},(2^{15}-1)]$ represents the range $[-\pi,((2^{15}-1)/2^{15})\pi]$
  - Accessible Z result data for circular and hyperbolic functions is integer in data form of S15
- Emulated LUT for linear function
  - Data form is 1 integer bit and 15-bit fractional part (1.15)
  - Accessible Z result data for linear function is rational number with fixed data form of S4.11 (signed 4Q16)
- Truncation Error
  - The result of a CORDIC calculation may return an approximation due to truncation of LSBs
  - Good accuracy of the CORDIC calculated result data, especially in circular mode
- Interrupt
  - On completion of a calculation

fractional divider) for generating a wide range of baud rates based on its input clock f_{PCLK}, see **Figure 30**.

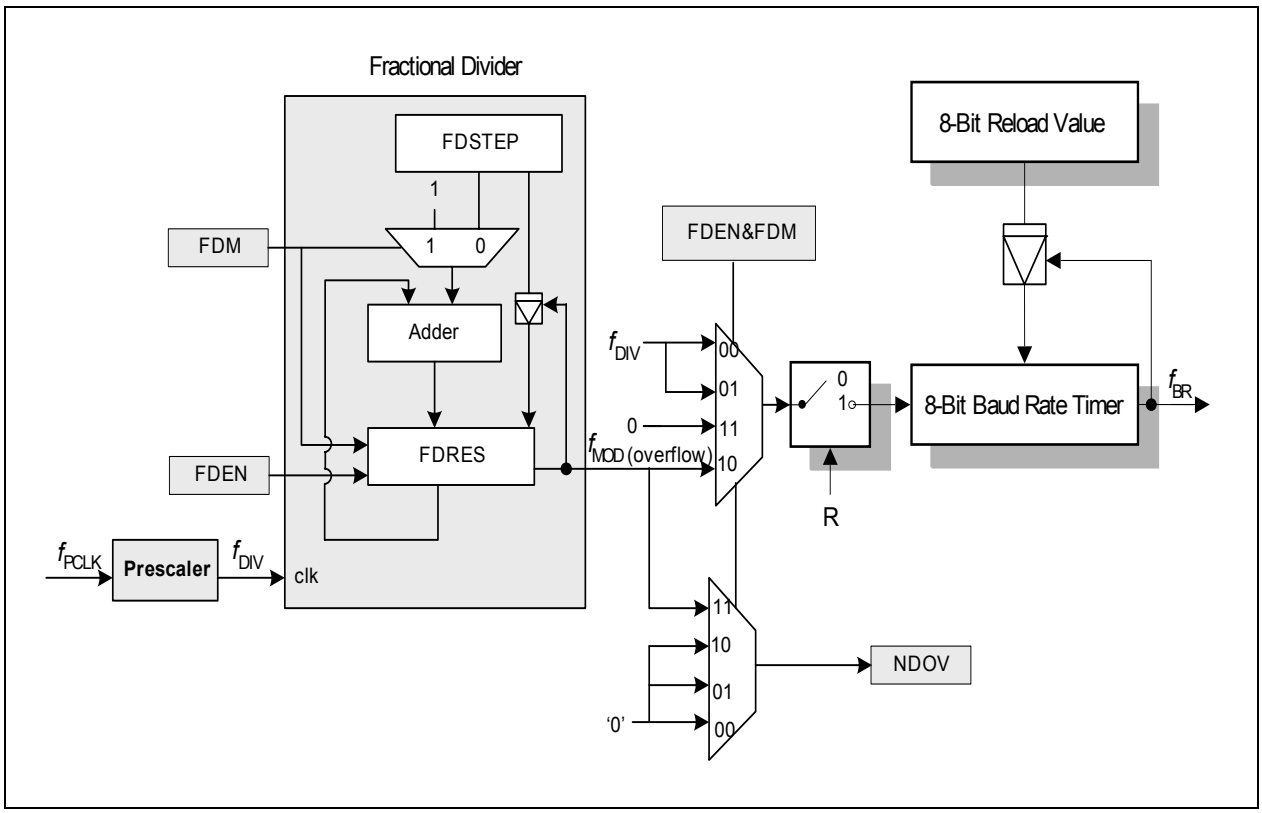


Figure 30 Baud-rate Generator Circuitry

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider (f_{MOD}) if the fractional divider is enabled (FDCON.FDEN = 1), or the output of the prescaler (f_{DIV}) if the fractional divider is disabled (FDEN = 0). For baud rate generation, the fractional divider must be configured to fractional divider mode (FDCON.FDM = 0). This allows the baud rate control run bit BCON.R to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode (FDEN = 1 and FDM = 1) stops the baud rate timer and nullifies the effect of bit BCON.R. See **Section 3.14**.

The baud rate (f_{BR}) value is dependent on the following parameters:

- Input clock f_{PCLK}
- Prescaling factor (2^{BRPRE}) defined by bit field BRPRE in register BCON
- Fractional divider (STEP/256) defined by register FDSTEP
  (to be considered only if fractional divider is enabled and operating in fractional divider mode)
- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \quad \text{where } 2^{BRPRE} \times (BR\_VALUE + 1) > 1 \tag{3.5}$$

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \times \frac{STEP}{256} \tag{3.6}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 24 MHz, the maximum achievable baud rate is 0.75 MBaud.

Standard LIN protocol can support a maximum baud rate of 20 kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20 kHz to 115.2 kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 30 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 24 MHz is used.

Table 30 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2BRPRE)	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000_B)	78 ($4E_H$)	0.17 %
9600 Baud	1 (BRPRE=000_B)	156 ($9C_H$)	0.17 %
4800 Baud	2 (BRPRE=001_B)	156 ($9C_H$)	0.17 %
2400 Baud	4 (BRPRE=010_B)	156 ($9C_H$)	0.17 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 31** lists the resulting deviation errors from generating a baud rate of 115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.

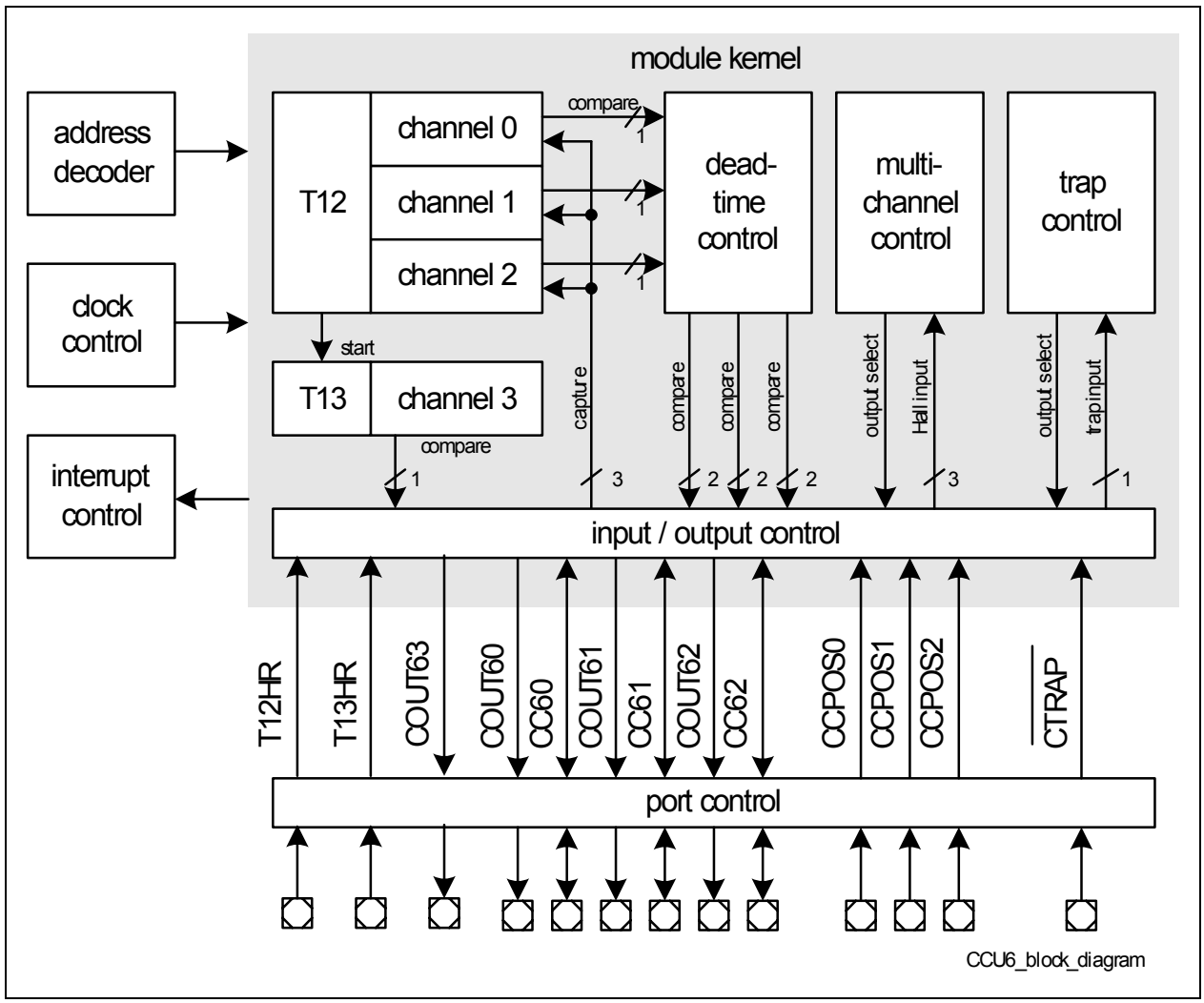


Figure 33 CCU6 Block Diagram

3.22 On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- Use the built-in debug functionality of the XC800 Core
- Add a minimum of hardware overhead
- Provide support for most of the operations by a Monitor Program
- Use standard interfaces to communicate with the Host (a Debugger)

Features

- Set breakpoints on instruction address and on address range within the Program Memory
- Set breakpoints on internal RAM address range
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks via JTAG and upon activating a dedicated pin
- Step through the program code

The OCDS functional blocks are shown in **Figure 37**. The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals.

After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack).

The OCDS system is accessed through the JTAG[1)], which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

Note: All the debug functionality described here can normally be used only after XC886/888 has been started in OCDS mode.

1) The pins of the JTAG port can be assigned to either the primary port (Port 0) or either of the secondary ports (Ports 1 and 2/Port 5).
User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.

Table 36 Chip Identification Number (cont'd)

Product Variant	Chip Identification Number		
	AA-Step	**AB-Step**	**AC-Step**
XC886-6FFA 3V3	-	$095D1562_H$	$0B5D1562_H$
XC888-6FFA 3V3	-	$095D1563_H$	$0B5D1563_H$
XC886CLM-8FFA 5V	-	09900102_H	$0B900102_H$
XC888CLM-8FFA 5V	-	09900103_H	$0B900103_H$
XC886LM-8FFA 5V	-	09900122_H	$0B900122_H$
XC888LM-8FFA 5V	-	09900123_H	$0B900123_H$
XC886CLM-6FFA 5V	-	09951502_H	$0B951502_H$
XC888CLM-6FFA 5V	-	09951503_H	$0B951503_H$
XC886LM-6FFA 5V	-	09951522_H	$0B951522_H$
XC888LM-6FFA 5V	-	09951523_H	$0B951523_H$
XC886CM-8FFA 5V	-	09980102_H	$0B980102_H$
XC888CM-8FFA 5V	-	09980103_H	$0B980103_H$
XC886C-8FFA 5V	-	09980142_H	$0B980142_H$
XC888C-8FFA 5V	-	09980143_H	$0B980143_H$
XC886-8FFA 5V	-	09980162_H	$0B980162_H$
XC888-8FFA 5V	-	09980163_H	$0B980163_H$
XC886CM-6FFA 5V	-	$099D1502_H$	$0B9D1502_H$
XC888CM-6FFA 5V	-	$099D1503_H$	$0B9D1503_H$
XC886C-6FFA 5V	-	$099D1542_H$	$0B9D1542_H$
XC888C-6FFA 5V	-	$099D1543_H$	$0B9D1543_H$
XC886-6FFA 5V	-	$099D1562_H$	$0B9D1562_H$
XC888-6FFA 5V	-	$099D1563_H$	$0B9D1563_H$
ROM Devices			
XC886CLM-8RFA 3V3	22400502_H	-	-
XC888CLM-8RFA 3V3	22400503_H	-	-
XC886LM-8RFA 3V3	22400522_H	-	-
XC888LM-8RFA 3V3	22400523_H	-	-
XC886CLM-6RFA 3V3	22411502_H	-	-
XC888CLM-6RFA 3V3	22411503_H	-	-

4.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the XC886/888. All parameters mentioned in the following table refer to these operating conditions, unless otherwise noted.

Table 37 Operating Condition Parameters

Parameter	Symbol	Limit Values		Unit	Notes/ Conditions
		min.	max.		
Digital power supply voltage	V_{DDP}	4.5	5.5	V	5V Device
Digital power supply voltage	V_{DDP}	3.0	3.6	V	3.3V Device
Digital ground voltage	V_{SS}	0		V	
Digital core supply voltage	V_{DDC}	2.3	2.7	V	
System Clock Frequency[1)]	f_{SYS}	88.8	103.2	MHz	
Ambient temperature	T_A	-40	85	°C	SAF-XC886/888...
		-40	125	°C	SAK-XC886/888...

1) f_{SYS} is the PLL output clock. During normal operating mode, CPU clock is f_{SYS} / 4. Please refer to **Figure 26** for detailed description.

Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Maximum current out of V_{SS}	I_{MVSS}	SR	–	120	mA	[3]
V_{DDP} = 3.3 V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 8 mA
			–	0.4	V	I_{OL} = 2.5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -8 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -2.5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on RESET pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on RESET pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis	HYS	CC	0.03 × V_{DDP}	–	V	CMOS Mode[1]
Input Hysteresis on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	[1]
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	

Table 43 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 3.3V Range					
Active Mode	I_{DDP}	25.6	31.0	mA	Flash Device[3]
		23.4	28.6	mA	ROM Device[3]
Idle Mode	I_{DDP}	19.9	24.7	mA	Flash Device[4]
		17.5	20.7	mA	ROM Device[4]
Active Mode with slow-down enabled	I_{DDP}	13.3	16.2	mA	Flash Device[5]
		11.5	13.7	mA	ROM Device[5]
Idle Mode with slow-down enabled	I_{DDP}	11.1	14.4	mA	Flash Device[6]
		9.3	11.4	mA	ROM Device[6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 3.3 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 3.6 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz(set by on-chip oscillator of 9.6 MHz and NDIV in PLL_CON to 1001_B), $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 8 MHz by setting CLKREL in CMCON to 0110_B, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 8 MHz by setting CLKREL in CMCON to 0110_B,, $\overline{\text{RESET}}$ = V_{DDP}, no load on ports.

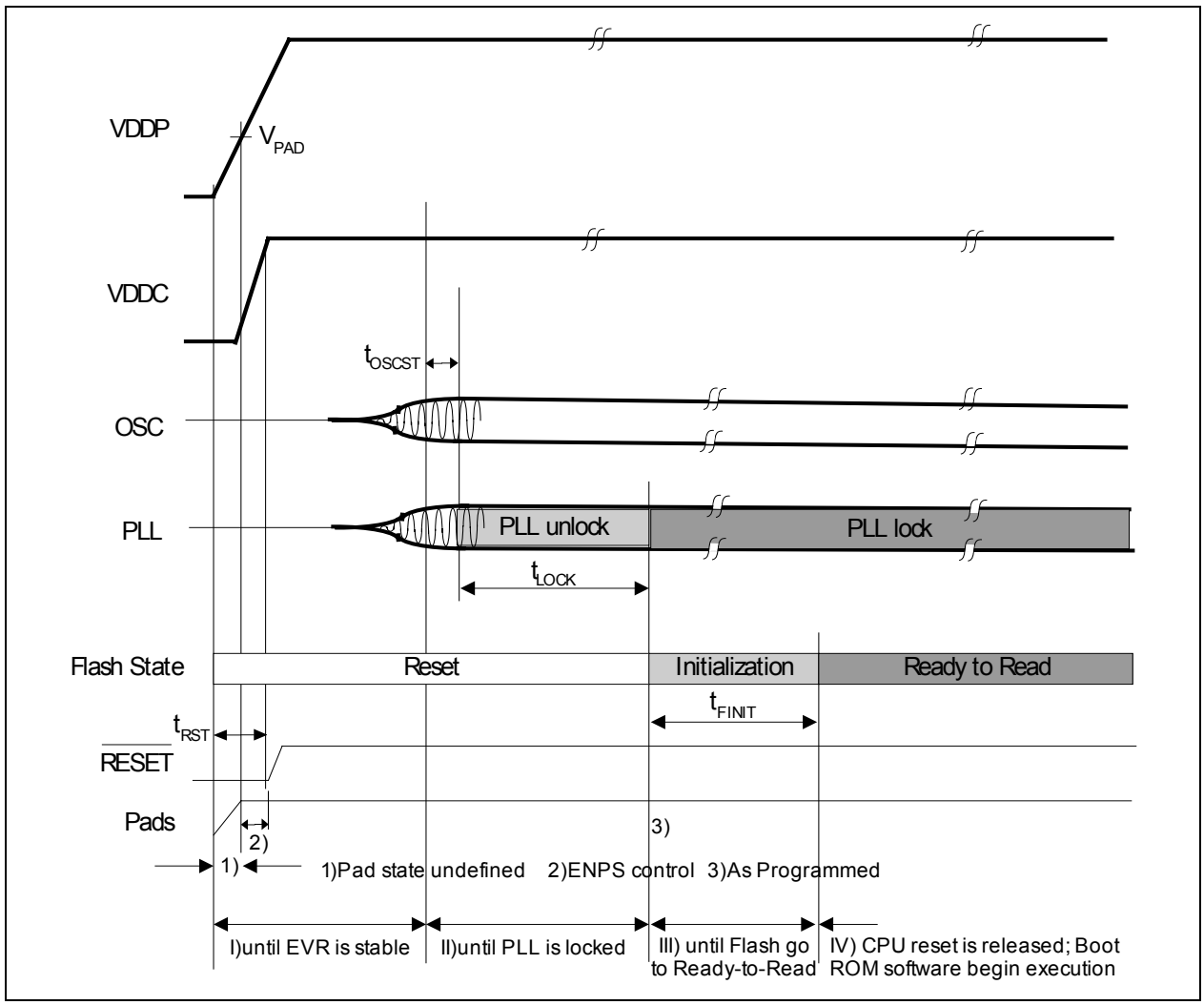


Figure 44 Power-on Reset Timing

4.3.5 External Clock Drive XTAL1

Table 48 shows the parameters that define the external clock supply for XC886/888. These timing parameters are based on the direct XTAL1 drive of clock input signals. They are not applicable if an external crystal or ceramic resonator is considered.

Table 48 External Clock Drive Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Oscillator period	t_{osc}	SR	83.3	250	ns	1)2)
High time	t_1	SR	25	-	ns	2)3)
Low time	t_2	SR	25	-	ns	2)3)
Rise time	t_3	SR	-	20	ns	2)3)
Fall time	t_4	SR	-	20	ns	2)3)

1) The clock input signals with 45-55% duty cycle are used.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

3) The clock input signal must reach the defined levels V_{ILX} and V_{IHX}.

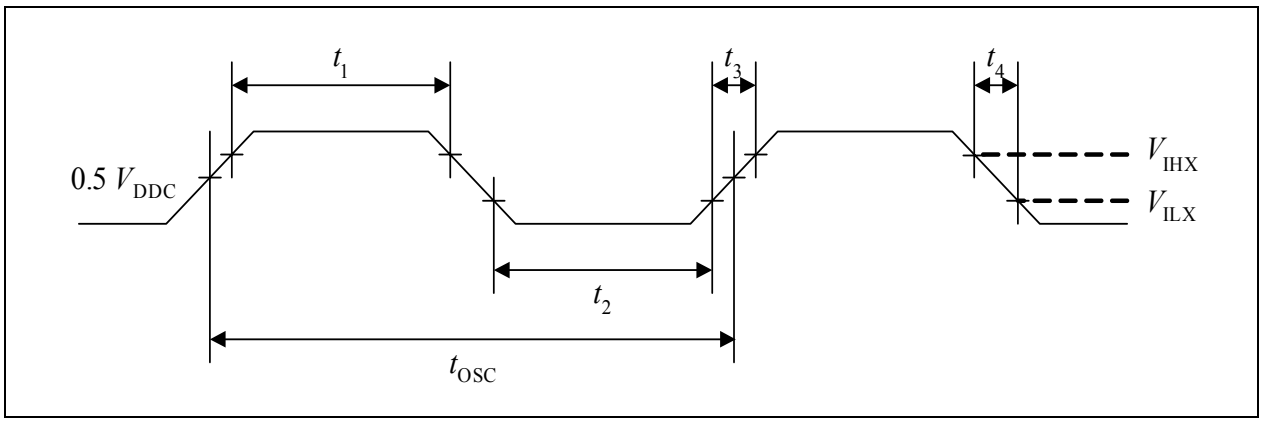


Figure 45 External Clock Drive XTAL1

5 Package and Quality Declaration

Chapter 5 provides the information of the XC886/888 package and reliability section.

5.1 Package Parameters

Table 1 provides the thermal characteristics of the package used in XC886 and XC888.

Table 1 Thermal Characteristics of the Packages

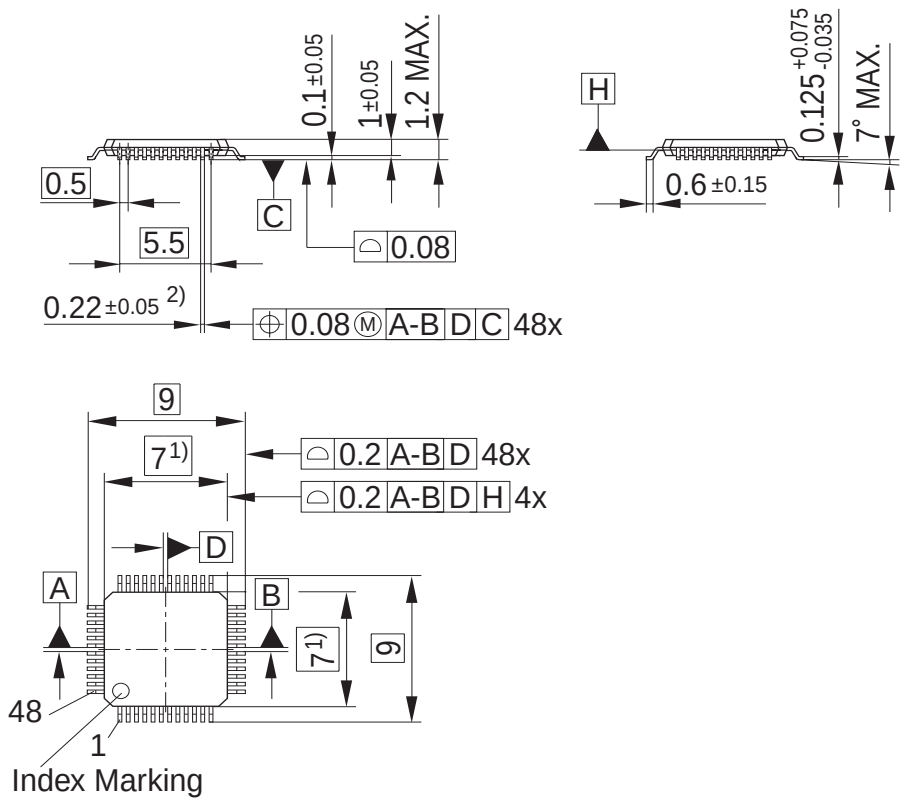
Parameter	Symbol		Limit Values		Unit	Notes
			Min.	Max.		
PG-TQFP-48 (XC886)						
Thermal resistance junction case	R_{TJC}	CC	-	13	K/W	1)2)
Thermal resistance junction lead	R_{TJL}	CC	-	32.5	K/W	1)2)
PG-TQFP-64 (XC888)						
Thermal resistance junction case	R_{TJC}	CC	-	12.6	K/W	1)2)
Thermal resistance junction lead	R_{TJL}	CC	-	33.4	K/W	1)2)

1) The thermal resistances between the case and the ambient (R_{TCA}) , the lead and the ambient (R_{TLA}) are to be combined with the thermal resistances between the junction and the case (R_{TJC}), the junction and the lead (R_{TJL}) given above, in order to calculate the total thermal resistance between the junction and the ambient (R_{TJA}). The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) depend on the external system (PCB, case) characteristics, and are under user responsibility.
The junction temperature can be calculated using the following equation: $T_J=T_A+R_{TJA} \times P_D$, where the R_{TJA} is the total thermal resistance between the junction and the ambient. This total junction ambient resistance R_{TJA} can be obtained from the upper four partial thermal resistances, by
a) simply adding only the two thermal resistances (junction lead and lead ambient), or
b) by taking all four resistances into account, depending on the precision needed.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

5.2 Package Outline

Figure 48 shows the package outlines of the XC886.



1) Does not include plastic or metal protrusion of 0.25 max. per side
2) Does not include dambar protrusion of 0.08 max. per side

GPP09237

Figure 48 PG-TQFP-48 Package Outline